

Foreword

The International Microelectronics and Packaging Society (IMAPS) is committed to the timely publication of the archival *Journal of Microelectronics and Electronic Packaging*. Today, the Journal draws papers from every corner of the world, and these papers are reviewed by an editorial board composed of thirteen experts from six different countries. As part of that commitment, we are constantly working to strengthen this publication in terms of content and format.

With this 1st quarter 2008 issue, you will notice a comprehensive change in the formatting and style from what we have published in the past. We hope that you will find this format both pleasing to the eye and more pleasant to read.

As in the past, this publication is available to all IMAPS members via web access (<http://www.imaps.org/jmep/index.htm>), and for a nominal fee, members can elect to receive a hardcopy of these issues as well. In addition, previous issues and individual papers are also available online to members through the journal access link noted above, and to non-members through the iKnow MicroelectronicsTM database (<http://www.imaps.org/imapsstore/default.aspx>).

Fred D. Barlow III, Ph.D.
Editor-in-Chief